

1762

To: Technology Center 1762
Facsimile Number: (703) 872-9306

Total Pages Sent: 6

From: David Denker
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-4388

RECEIVED
CENTRAL FAX CENTER

JUN 21 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

OFFICIAL

In re the application of: Smith *et al.*

Docket: TI-22782B

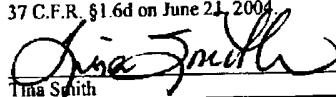
Appl. No.: 09/757,073

Examiner: E. Cameron

Filed: 1/8/01

Art Unit: 1762

For: Polyol-Based Method For Forming Thin Film Aerogels On Semiconductor Substrates

FACSIMILE CERTIFICATE	
I hereby certify that this correspondence is being transmitted by Facsimile to the Patent and Trademark Office in accordance with 37 C.F.R. §1.6d on June 21, 2004.	
	
Tina Smith	

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET (1 SHEET)	<input checked="" type="checkbox"/> AMENDMENT 111.1 (2 Pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (# Pages)
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> NOTICE OF APPEAL (# Pages)
<input type="checkbox"/> ASSIGNMENT	<input checked="" type="checkbox"/> TERMINAL DISCLAIMER
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE
<input type="checkbox"/> INFORMAL DRAWINGS	<input checked="" type="checkbox"/> PETITION TO ACCEPT UNINTENTIONALLY DELAYED CLAIM FOR PRIORITY
<input type="checkbox"/> CONTINUATION APPN	
<input type="checkbox"/> DIVISIONAL APPN	
NAME OF INVENTOR(S): Smith, et al.	
TITLE OF INVENTION: Polyol-Based Method for Forming Thin Film Aerogels on Semiconductor Substrates	
TI FILE NO.: TI-22782B	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6/21/04 DUE: 7/19/04	
ATTY/SECY: DD/tms	
RECEIPT DATE & SERIAL NO.: Appl. No.: 09/757,073 Filing Date: 1/08/01	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75074